

X7R with KONNEKT Technology

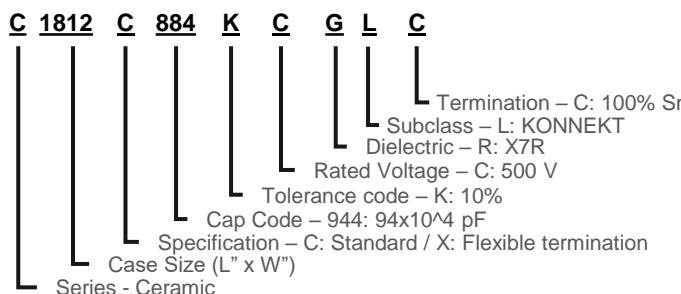
Overview

X7R with KONNEKT™ technology surface mount capacitors are designed for applications where higher capacitance and voltage are needed without requiring additional board space. KONNEKT high density packaging technology uses a proprietary Transient Liquid Phase Sintering (TLPS) material to create a surface mount multi-chip solution for high density packaging.

Benefits

Commercial and Automotive grade (AEC-Q200)
Stacked design saves PCB area.
Lead (Pb)-free, RoHS, and REACH compliant
Surface mount capable with standard reflow

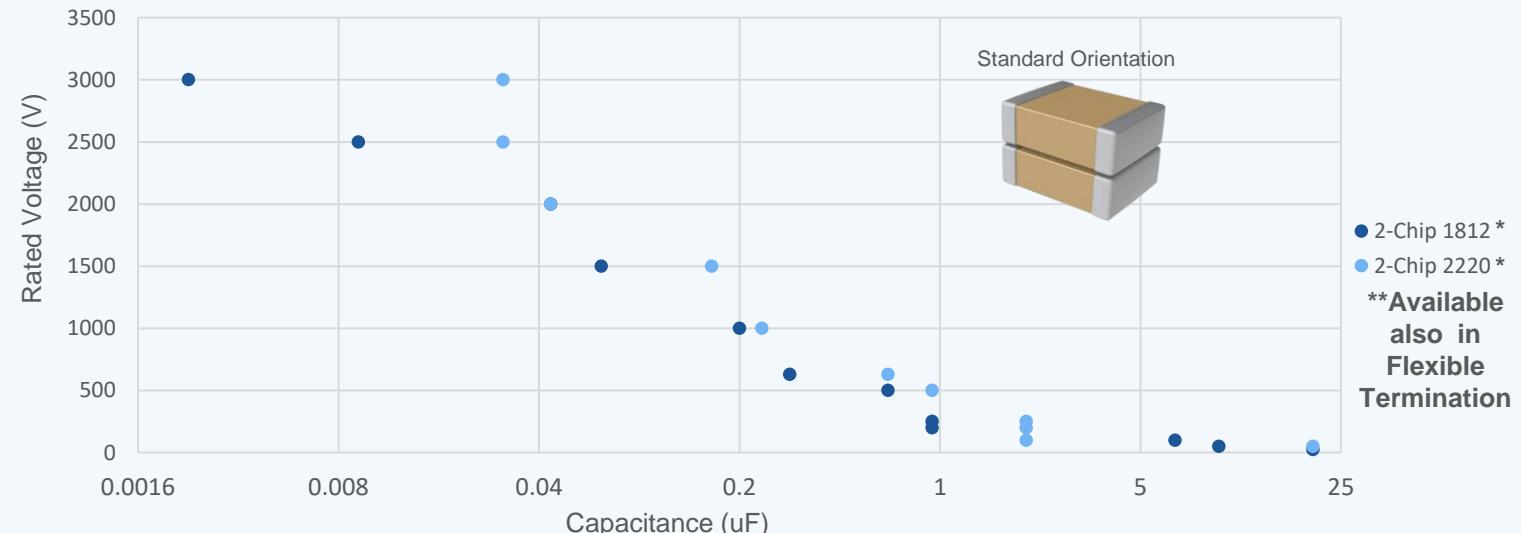
Part Number System



Electrical Characteristics

Operating Temperature	-55°C to +125°C
Rated Capacitance	2.4 nF – 20 uF (±10% tol.)
Rated Voltage	25 V – 3,000 V
EIA Case Size	1812 and 2220

X7R with KONNEKT Selection Guide



Applications

SMPS (Switch Mode Power Supplies)	Industrial and medical equipment
Lighting ballasts, HID lighting	Filters
DC/DC Converters	Snubbers
Telecom equipment	DC Blocking

<https://ec.kemet.com/konnekt>